

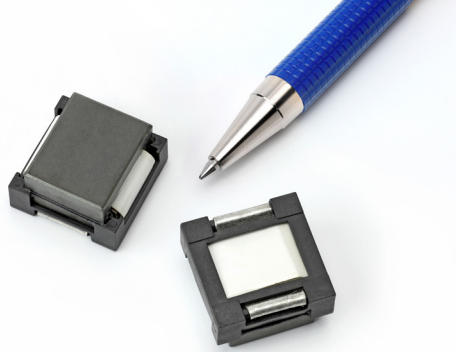


**THE DATASHEET OF
HC2LP-2R2-R**



HC2LP

Low profile, high current power inductors



Product description

- Compact footprint
- Designed for high density, high current/low voltage applications
- Foil technology that adds higher reliability factor over the traditional magnet wire used for higher frequency circuit designs
- Frequency Range up to 1MHz
- Ferrite core material

Applications

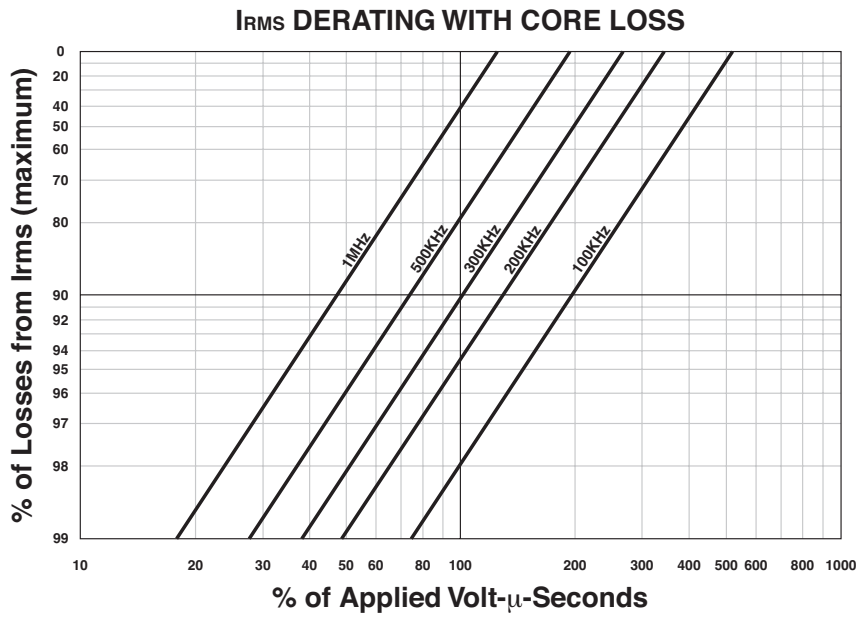
- Distributed power systems DC-DC converters
- General-purpose low voltage supplies
- Computer systems
- Servers
- Point of Load (POL) converters
- Industrial Equipment
- Networking/Telecom power supplies

Environmental data

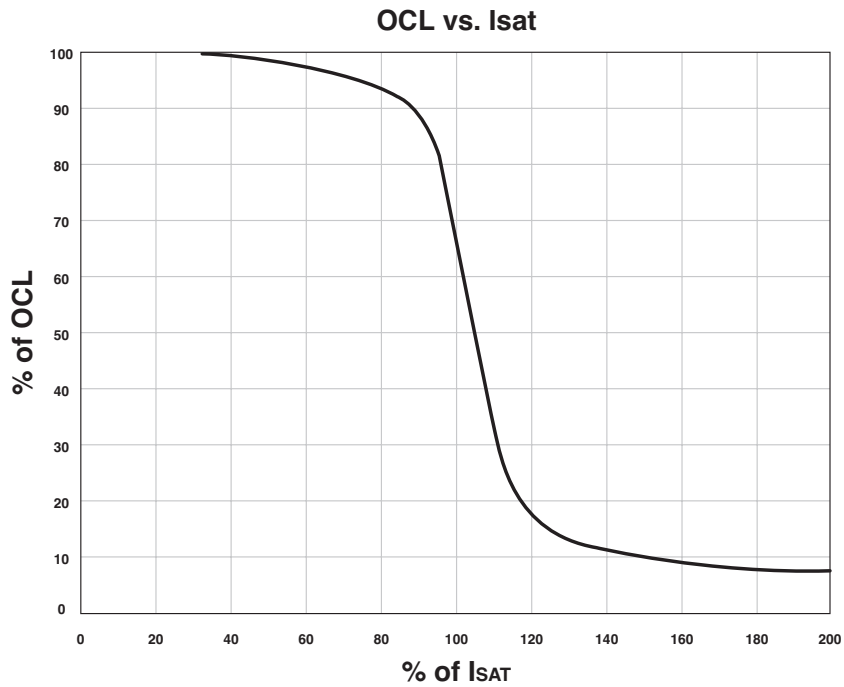
- Storage temperature range (component): -40°C to +125°C
- Operating temperature range: -40°C to +125°C (ambient + self-temperature rise).
- Solder reflow temperature: J-STD-020D compliant.



Core loss



Inductance Characteristics



Solder reflow profile

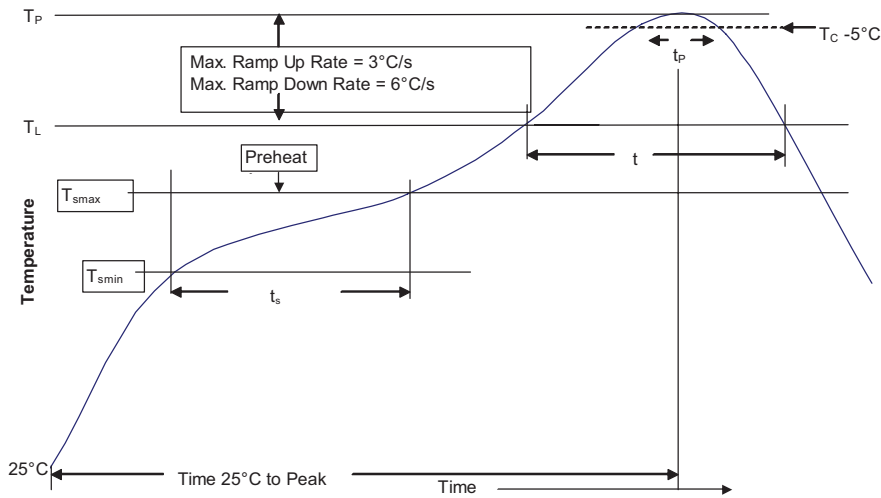


Table 1 - Standard SnPb Solder (T_C)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5mm)	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T_C)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350 - 2000	Volume mm ³ >2000
<1.6mm	260°C	260°C	260°C
1.6 - 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Reference JDEC J-STD-020D

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak		
• Temperature min. (T _{smin})	100°C	150°C
• Temperature max. (T _{smax})	150°C	200°C
• Time (T _{smin} to T _{smax}) (t _s)	60-120 Seconds	60-120 Seconds
Average ramp up rate T _{smax} to T _P	3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature (T _L)	183°C	217°C
Time at liquidous (t _L)	60-150 Seconds	60-150 Seconds
Peak package body temperature (T _P)*	Table 1	Table 2
Time (t _P)** within 5 °C of the specified classification temperature (T _C)	20 Seconds**	30 Seconds**
Average ramp-down rate (T _P to T _{smax})	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

* Tolerance for peak profile temperature (T_P) is defined as a supplier minimum and a user maximum.

** Tolerance for time at peak profile temperature (t_P) is defined as a supplier minimum and a user maximum.

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